

**In the Specification**

Please add the following sentence to the end of the paragraph ending on line 11, page 1:

This Application is a continuation of pending U.S. Utility Application entitled "**Backplane, Printed Wiring Board, And/Or Multi-Chip Module-Level Optical Interconnect Layer Having Embedded Air-Gap Technologies And Methods Of Fabrication**", having Serial No. 10/135,314, filed April 29, 2002.

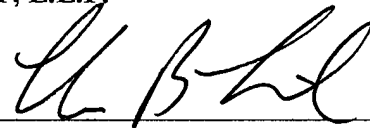
**REMARKS**

Favorable action in regard to the application is earnestly solicited.

Respectfully submitted,

**THOMAS, KAYDEN, HORSTEMEYER  
& RISLEY, L.L.P.**

By:



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Docket No. 62004-1851